SDLS131 - APRIL 1985 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

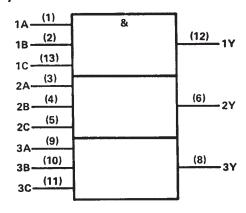
These devices contain three independent 3-input AND gates.

The SN54LS11 and SN54S11 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 °C. The SN74LS11 and SN74S11 are characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE (each gate)

| II | VPUT | s | OUTPUT |
|----|------|---|--------|
| Α | В | С | Y |
| Н | Н | н | Н |
| L | X | X | L |
| × | L | x | L |
| х | X | L | L |

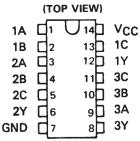
logic symbol†



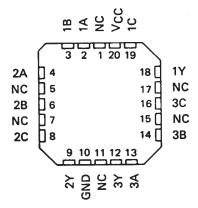
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS11, SN74S11 . . . J OR W PACKAGE SN74LS11, SN74S11 . . . D OR N PACKAGE

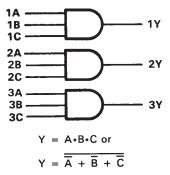


SN54LS11, SN54S11 . . . FK PACKAGE (TOP VIEW)

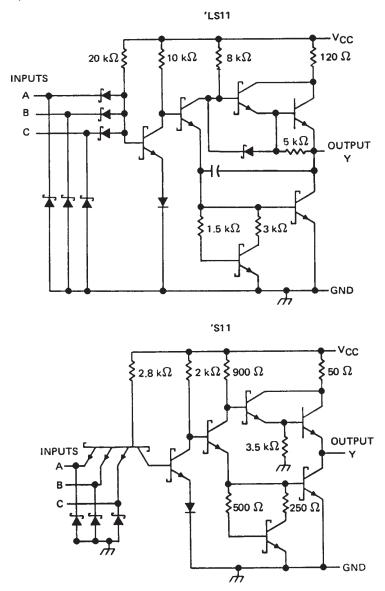


NC-No internal connection

logic diagram (positive logic)



schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| | 7 V |
|--------------------------------------|-------------------|
| Input voltage: 'S11 | 5.5 V |
| 'LS11 | 7 V |
| Operating free-air temperature range | SN54' |
| | SN74' 0°C to 70°C |
| Storage temperature range | 65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

| | | | SN54LS1 | 11 | S | N74LS1 | 1 | UNIT |
|-----|--------------------------------|------|---------|-------|------|--------|-------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | ONT |
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| VIH | High-level input voltage | 2 | | | 2 | | | V |
| VIL | Low-level input voltage | | | 0.7 | | | 0.8 | ٧ |
| ЮН | High-level output current | | | - 0.4 | | | - 0.4 | mA |
| loL | Low-level output current | | | 4 | | | 8 | mA |
| TA | Operating free-air temperature | - 55 | | 125 | 0 | | 70 | °c |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | | 7507 00401 | | SN54LS | 11 | S | N74LS1 | 1 | UNIT | |
|-------------------|------------------------|--------------------------|----------------------------|--------|------|--------------|--------|-------|-------|------|
| PARAMETER | | TEST CONDI | TIONS T | MIN | TYP‡ | MAX | MIN | TYP ‡ | MAX | UNIT |
| VIK | V _{CC} = MIN, | I _I = - 18 mA | | | | – 1.5 | | | - 1.5 | ٧ |
| Vон | V _{CC} = MIN, | V _{IH} = 2 V, | I _{OH} = - 0.4 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | V |
| V | V _{CC} = MIN, | VIL = MAX, | I _{OL} = 4 mA | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| VOL | V _{CC} = MIN, | VIL = MAX, | I _{OL} = 8 mA | | | | | 0.35 | 0.5 | V |
| 11 | V _{CC} = MAX, | V _I = 7 V | | | | 0.1 | | | 0.1 | mA |
| Чн | V _{CC} = MAX, | V ₁ = 2.7 V | | | | 20 | | | 20 | μΑ |
| IIL. | V _{CC} = MAX, | V ₁ = 0.4 V | | | | - 0.4 | | | - 0.4 | mA |
| I _{OS} § | V _{CC} = MAX | | | - 20 | | - 100 | - 20 | | - 100 | mA |
| Іссн | V _{CC} = MAX, | V ₁ = 4.5 V | | | 1.8 | 3.6 | | 1.8 | 3.6 | mA |
| ICCL | V _{CC} = MAX, | V _I = 0 V | | | 3.3 | 6.6 | | 3.3 | 6.6 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CON | DITIONS | MIN | TYP | MAX | UNIT |
|------------------|-----------------|----------------|---------------------|------------------------|-----|-----|-----|------|
| ^t PLH | A, B or C | > | $R_1 = 2 k\Omega$, | C ₁ = 15 pF | | 8 | 15 | ns |
| tPHL | A, B 01 0 | ' | 11 - 2 K32, | CL - 15 pr | | 10 | 20 | ns |

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

| | | | SN54S11 | | | SN74S11 | | UNIT |
|-----|--------------------------------|------|---------|-----|------|---------|------------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | ٧ |
| VIH | High-level input voltage | 2 | | | 2 | | | ٧ |
| VIL | Low-level input voltage | | | 0.8 | | | 0.8 | ٧ |
| ЮН | High-level output current | | | - 1 | | | – 1 | mA |
| lor | Low-level output current | | | 20 | | | 20 | mA |
| TA | Operating free-air temperature | - 55 | | 125 | 0 | | 70 | °c |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| | | 7507 0011017 | 10110 + | | SN54S1 | 1 | | SN74S11 | 1 | UNIT |
|-----------------|------------------------|--------------------------|--------------------------|-----|--------|-------|------|---------|-------|-------|
| PARAMETER | | TEST CONDIT | IONS T | MIN | TYP ‡ | MAX | MIN | TYP ‡ | MAX | CIVIT |
| VIK | V _{CC} = MIN, | I ₁ = - 18 mA | | | | - 1.2 | | | - 1.2 | ٧ |
| V _{OH} | V _{CC} = MIN, | V _{IH} = 2 V, | I _{OH} = - 1 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | ٧ |
| VOL | V _{CC} = MIN, | V _{1L} = 0.8 V, | 1 _{OL} = 20 mA | | | 0.5 | | | 0.5 | ٧ |
| I _I | V _{CC} = MAX, | V _I = 5.5 V | | | | 1 | | | 1 | mA |
| lн | V _{CC} = MAX, | V _I = 2.7 V | | | | 50 | | | 50 | μА |
| l _{IL} | V _{CC} = MAX, | V ₁ = 0.5 V | | | | - 2 | | | - 2 | mA |
| IOS § | V _{CC} = MAX | | | -40 | | - 100 | - 40 | | - 100 | mA |
| Іссн | V _{CC} = MAX, | V _I = 4.5 V | | | 13.5 | 24 | | 13.5 | 24 | mA |
| ICCL | V _{CC} = MAX, | V1 = 0 V | | | 24 | 42 | | 24 | 42 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CON | IDITIONS | MIN | ТҮР | MAX | UNIT |
|------------------|-----------------|----------------|-------------------------|------------------------|-----|-----|-----|------|
| ^t PLH | | | P. = 290 O | C. = 15 oF | | 4.5 | 7 | ns |
| ^t PHL | A, B or C | Y | R _L = 280 Ω, | C _L = 15 pF | | 5 | 7.5 | ns |
| ^t PLH | A, B 01 C | * | D 200 O | 2 - 52 - 5 | 6 | 6 | | ns |
| tpHL | | | $R_L = 280 \Omega$, | C _L = 50 pF | | 7.5 | | ns |

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





9-Oct-2020

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|------------|--------------|--------------------|------|----------------|----------------------------|-------------------------------|--------------------|--------------|-------------------------|---------|
| JM38510/08001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 08001BCA | Sample |
| JM38510/08001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 08001BDA | Sample |
| JM38510/31001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 31001BCA | Sample |
| JM38510/31001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 31001BDA | Sample |
| M38510/08001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 08001BCA | Samples |
| M38510/08001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 08001BDA | Sample |
| M38510/31001BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 31001BCA | Sample |
| M38510/31001BDA | ACTIVE | CFP | W | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 31001BDA | Sample |
| SN54LS11J | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | SN54LS11J | Sample |
| SN54S11J | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | SN54S11J | Sample |
| SN74LS11D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS11 | Sample |
| SN74LS11DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS11 | Sample |
| SN74LS11DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS11 | Sample |
| SN74LS11N | ACTIVE | PDIP | N | 14 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS11N | Sample |
| SN74LS11NE4 | ACTIVE | PDIP | N | 14 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS11N | Sample |
| SN74LS11NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS11 | Sample |
| SNJ54LS11FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | SNJ54LS 11FK | Sample |



PACKAGE OPTION ADDENDUM

9-Oct-2020

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|------------|--------------|--------------------|------|----------------|----------|-------------------------------|--------------------|--------------|-------------------------|---------|
| SNJ54LS11J | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | SNJ54LS11J | Samples |
| SNJ54LS11W | ACTIVE | CFP | W | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | SNJ54LS11W | Samples |
| SNJ54S11J | ACTIVE | CDIP | J | 14 | 1 | TBD | SNPB | N / A for Pkg Type | -55 to 125 | SNJ54S11J | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL. Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



PACKAGE OPTION ADDENDUM

9-Oct-2020

OTHER QUALIFIED VERSIONS OF SN54LS11, SN74LS11:

• Military: SN54LS11

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 8-Apr-2013

TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN74LS11DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |

www.ti.com 8-Apr-2013



*All dimensions are nominal

| ĺ | Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| | SN74LS11DR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Tl's products are provided subject to Tl's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such Tl products. Tl's provision of these resources does not expand or otherwise alter Tl's applicable warranties or warranty disclaimers for Tl products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated